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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/506,510	09/03/2004	Teruo Amoh	50395-279	3062
20277 MCDERMOT	7590 03/21/2007 Γ WILL & EMERY LLP	EXAMINER		
600 13TH STREET, N.W.			NGO, NGAN V	
WASHINGTON, DC 20005-3096			ART UNIT	PAPER NUMBER
			2818	
SHORTENED STATUTOR	RY PERIOD OF RESPONSE	MAIL DATE	DELIVERY MODE	
3 MONTHS		03/21/2007	PAPER	

Please find below and/or attached an Office communication concerning this application or proceeding.

If NO period for reply is specified above, the maximum statutory period will apply and will expire 6 MONTHS from the mailing date of this communication.

		Application No.	Applicant(s)
		10/506,510	AMOH ET AL.
Office Action Summary		Examiner	Art Unit
		Ngan Ngo	2818
Period 1	The MAILING DATE of this communication apports.	pears on the cover sheet w	rith the correspondence address
A SI WHI - Ext afte - If N - Fai Any	HORTENED STATUTORY PERIOD FOR REPL CHEVER IS LONGER, FROM THE MAILING D ensions of time may be available under the provisions of 37 CFR 1. or SIX (6) MONTHS from the mailing date of this communication. O period for reply is specified above, the maximum statutory period ure to reply within the set or extended period for reply will, by statute or reply received by the Office later than three months after the mailing patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNI 136(a). In no event, however, may a will apply and will expire SIX (6) MO e, cause the application to become A	CATION.  reply be timely filed  NTHS from the mailing date of this communication. BANDONED (35 U.S.C. § 133).
Status	,		
1)⊠ 2a)⊑ 3)⊡	This action is <b>FINAL</b> . 2b)⊠ This	s action is non-final. nce except for formal mat	, <b>,</b>
Disnosi	tion of Claims	•	,
5)□ 6)⊠ 7)□	Claim(s) 1-10 is/are pending in the application 4a) Of the above claim(s) is/are withdra Claim(s) is/are allowed. Claim(s) 1-10 is/are rejected. Claim(s) is/are objected to. Claim(s) are subject to restriction and/or	wn from consideration.	·
Applica	tion Papers		
10)	The specification is objected to by the Examine The drawing(s) filed on is/are: a) acc Applicant may not request that any objection to the Replacement drawing sheet(s) including the correct The oath or declaration is objected to by the Example 1.	epted or b) objected to drawing(s) be held in abeya tion is required if the drawing	nce. See 37 CFR 1.85(a). g(s) is objected to. See 37 CFR 1.121(d).
Priority	under 35 U.S.C. § 119	·	
a	Acknowledgment is made of a claim for foreign All b) Some * c) None of:  1. Certified copies of the priority document 2. Certified copies of the priority document 3. Copies of the certified copies of the priority application from the International Burea See the attached detailed Office action for a list	ts have been received. ts have been received in A rity documents have beer u (PCT Rule 17.2(a)).	Application No  received in this National Stage
2)	nt(s) ce of References Cited (PTO-892) ce of Draftsperson's Patent Drawing Review (PTO-948) rmation Disclosure Statement(s) (PTO/SB/08) er No(s)/Mail Date	Paper No(	Summary (PTO-413) s)/Mail Date nformal Patent Application

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The amendment filed February 26, 2007 has been entered and made of record as paper no. 0207.

Claims 1-10 are rejected under 35 U.S.C. 112, first paragraph, as failing to comply with the written description requirement. The claim(s) contains subject matter which was not described in the specification in such a way as to reasonably convey to one skilled in the relevant art that the inventor(s), at the time the application was filed, had possession of the claimed invention. The "surface roughness, Ra, of at most 0.18 µm before the solder layer is melted" as disclosed by the specification. The surface roughness, Ra, of at most 0.18 µm in the final structure is not disclosed by the specification.

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1-4 and 6-8 insofar as understood are rejected under 35 U.S.C. 103(a) as being unpatentable over Slater, Jr. et al (US 2003/0015721 A1) in view of Shizuki et al (US 5,914,536).

Slater, Jr. et al discloses a submount comprising a submount substrate (75), a solder layer (80) formed on the top surface of the submount substrate, and a semiconductor light-emitting device (100) mounted on the solder layer. Note paragraph [0061] of Slater. Shizuki further teaches that the surface roughness of the solder layer is

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less than 0.18 µm. Note lines 55-58, column 9 of Shizuki et al. Therefore it would have been obvious to one of ordinary skill in the art to use the teachings of Shizuki to form a surface roughness of the solder layer being less than 0.18 µm in Slater's device

In re claim 6-8, Slater discloses the barrier layer (35).

Claims 5 and 10 stand rejected under 35 U.S.C. 103(a) as being unpatentable over Slater, Jr. et al (US 2003/0015721 A1) in view of Shizuki et al (US 5,914,536) and further in view of Hikasa et al (US 5770821) and Kitaoka et al (US 2001/0053167 A1).

Slater and Shizuki disclose all the subject matter discussed above. Hikasa further teaches that the top surface of the submount substrate is less than 0.10 µm. Note lines 61-63, column 5 of Hikasa. Kitaoka et al further teaches that the submount is formed of AlN. Note paragraph [0105]. Therefore, it would have been obvious to one of ordinary skill in the art to use the teachings of Slater, Shizuki, Hikasa and Kitaoka to form the claimed structure.

Applicant's arguments filed February 26, 2007 have been fully considered but they are not persuasive.

In response to Applicant's arguments on page 6, the claimed device is a final product, not an intermediate product as argued.

The other references are cited to show other structures pertinent to Applicant's disclosure. All of these references disclose the surface roughness of the solder layer being less than 0.18 µm.

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Any inquiry concerning this communication should be directed to Examiner Ngan Ngo at telephone number (571) 272-1711. The fax phone number for the organization where this application or proceeding is assigned is (571)-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

, atantian

Ngan Van Ngo Primary Examiner

Ngan Ngo

March 15, 2007